# XN01507 (XN1507)

## Silicon NPN epitaxial planer transistor

For high break down voltage and low noise amplification

## Features

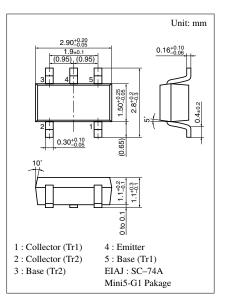
- Two elements incorporated into one package. (Emitter-coupled transistors)
- Reduction of the mounting area and assembly cost by one half.

## Basic Part Number of Element

• 2SD0814(2SD814) × 2 elements

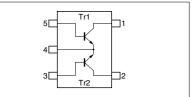
Parameter		Symbol	Ratings	Unit	
Rating of element	Collector to base voltage	V <sub>CBO</sub>	150	V	
	Collector to emitter voltage	V <sub>CEO</sub>	150	V	
	Emitter to base voltage	$V_{EBO}$	5	V	
	Collector current	I <sub>C</sub>	50	mA	
	Peak collector current	I <sub>CP</sub>	100	mA	
Overall	Total power dissipation	P <sub>T</sub>	300	mW	
	Junction temperature	Tj	150	°C	
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

## Absolute Maximum Ratings (Ta=25°C)



## Marking Symbol: 40

#### Internal Connection

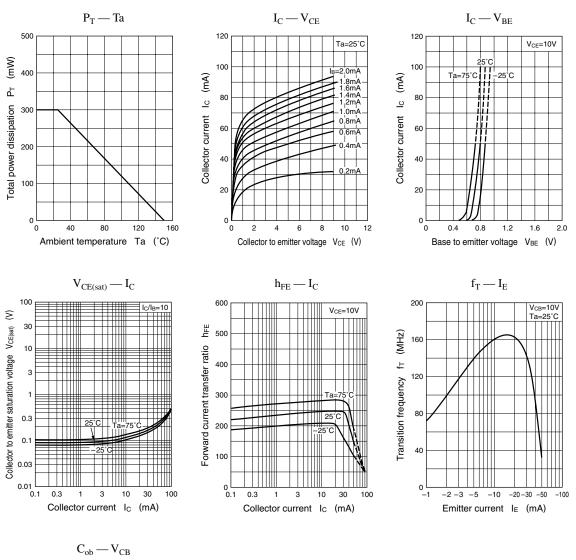


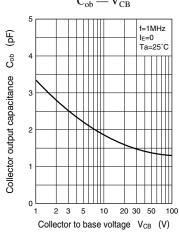
### Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = 100 \mu A, I_{\rm B} = 0$	150			V
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	5			v
Collector cutoff current	I <sub>CBO</sub>	$V_{CB} = 100V, I_E = 0$			1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 5V, I_C = 10mA$	90		450	
Forward current transfer $h_{FE}$ ratio	h <sub>FE</sub> (small/large) <sup>*1</sup>	$V_{CE} = 5V, I_{C} = 10mA$	0.5	0.99		
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 30 {\rm mA}, I_{\rm B} = 3 {\rm mA}$			1	V
Transition frequency	f <sub>T</sub>	$V_{CB} = 10V, I_E = -10mA, f = 200MHz$		150		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10V, I_E = 0, f = 1MHz$		2.3		pF

\*1 Ratio between 2 elements

Note) The Part number in the Parenthesis shows conventional part number.





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